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NO. 015 P. 11

SEP 13 2006

Application No.: 10/802,549

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Docket No.: 524322000600

REMARKS

In a non-final Office Action mailed on June 14, 2006, claims 1-15 and 21-25 are pending. By way of this amendment, new claims 26 and 27 have been added. Applicant respectfully requests reconsideration of these pending claims.

I. Rejection of Claims 1, 5, and 8 under 35 U.S.C. § 102(e)

The Examiner rejected claims 1, 5, and 8 under 35 U.S.C. § 102(e) as being anticipated by U.S. Publication No. US 2003/0094965 A1 ("the Tseng reference").

Claim 1 recites "obtaining a die placement of dice to be formed on the wafer." (Emphasis added.) Therefore, the "die placement" recited in claim 1 is of dice that will be formed on the wafer in a future fabrication process.

In rejecting claim 1, the Examiner cites to FIGs 1 and 2 of the Tseng reference as disclosing the recited die placement. The first step (step 10) in the electrical testing process depicted in FIG. 1 of the Tseng reference is to "provide substrate having series of die fabricated therein." (Emphasis added.) Additionally, paragraph [0025] of the Tseng reference discloses:

"[t]here is provided by the present invention, an electrical test method for electrical test testing a microelectronic fabrication die fabricated within a microelectronic fabrication substrate, wherein the microelectronic fabrication die fabricated within the microelectronic fabrication substrate is more accurately and efficiently tested." (Emphasis added.)

Thus, the substrate that is tested in the electrical testing process depicted in FIG. 1 has dice that have already been fabricated on the substrate.

Paragraph [0024] of the Tseng reference discloses that FIG. 2 shows a semiconductor integrated circuit microelectronic fabrication substrate wafer map. Lines 1-5 of paragraph [0048] discloses that the wafer map depicted in FIG. 2 is for a substrate wafer subsequent to a first electrical probe testing. As noted above, the substrate that is tested in the electrical testing process

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disclosed in the Tseng reference has dice that have already been fabricated on the substrate. Thus, the wafer map depicted in FIG. 2 is for a substrate with dice that have already been fabricated on the substrate.

Because the Tseng reference fails to disclose or suggest, "obtaining a die placement of dice to be formed on the wafer" or "adjusting the die placement" as recited in independent claim 1, Applicant asserts that claim 1 is allowable. Applicant also asserts that claims 5 and 8, which depend from claim 1, are allowable for at least the reason that they depend from an allowable independent claim.

II. Allowable Subject Matter

The Applicant thanks the Examiner for indicating claims 12-15 and 21-25 are allowable.

The Examiner indicated claims 2-4, 6-7, and 9-11 are objected to as being dependent upon the rejected base claim 1, but allowable. Applicant asserts that claims 2-4, 6-7, and 9-11, which depend from claim 1, are allowable for at least the reason that they depend from an allowable independent claim.

The Examiner indicated claims 3-4 and 7 are allowable if rewritten in independent form because they are dependent on objected claims 2 and 6. Applicant asserts that claim 3-4 and 7, which depend from claim 1, are allowable for at least the reason that they depend from an allowable independent claim.

III. New Claims

New independent claim 26 recites, in part, "obtaining a die placement of dice to be formed on the wafer" and "adjusting the die placement." Thus, Applicant asserts that new claim 26 is allowable for at least the same reasons as set forth above with regard to claims 1, 12, and 21. Applicant also asserts that new claim 27 is allowable for at least the reason that it depends from an allowable independent claim.

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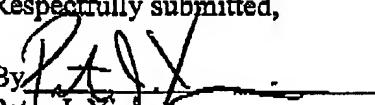
IV. Conclusion

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue. If it is determined that a telephone conference would expedite the prosecution of this application, the Examiner is invited to telephone the undersigned at the number given below.

In the event that the U.S. Patent and Trademark office determines that an extension and/or other relief is required, Applicant petitions for any required relief including extensions of time and authorizes the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to Deposit Account No. 03-1952 referencing docket no. 524322000600. However, the Commissioner is not authorized to charge the cost of the issue fee to the Deposit Account.

Dated: September 13, 2006

Respectfully submitted,

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